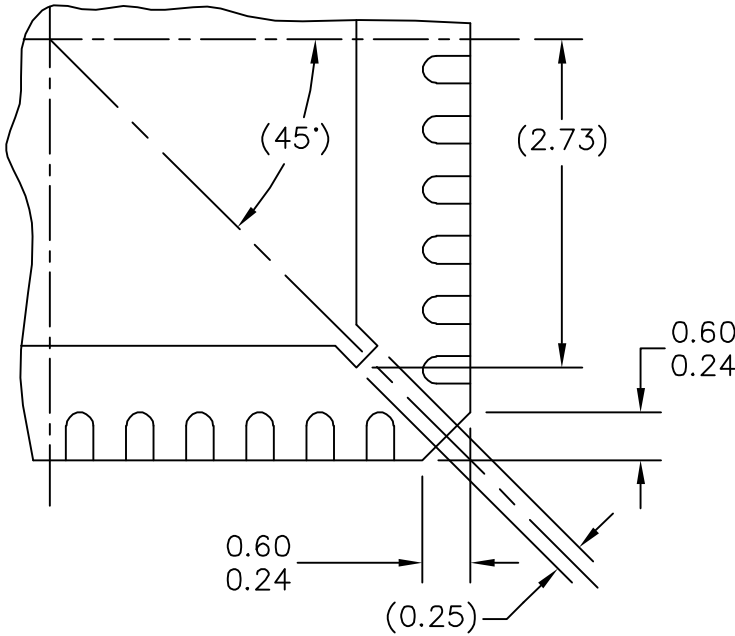
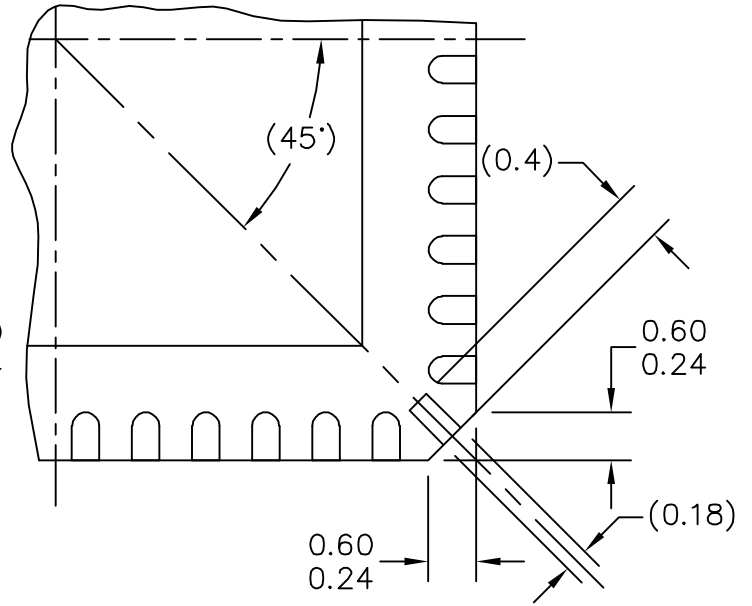


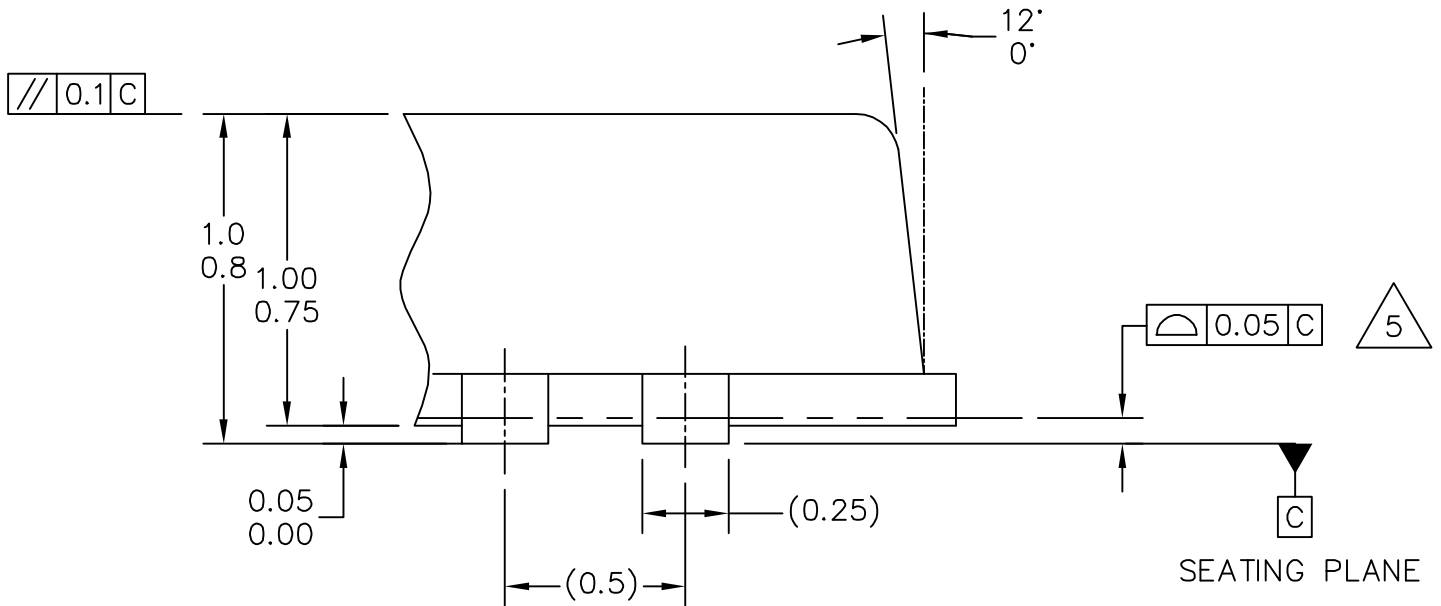
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 48 TERMINAL, 0.5 PITCH (7 X 7 X 1)	DOCUMENT NO: 98ASA10676D REV: A	
	STANDARD: JEDEC-MO-220 VKKD-2	
	SOT619-20 11 MAR 2016	



DETAIL N
PREFERRED CORNER CONFIGURATION

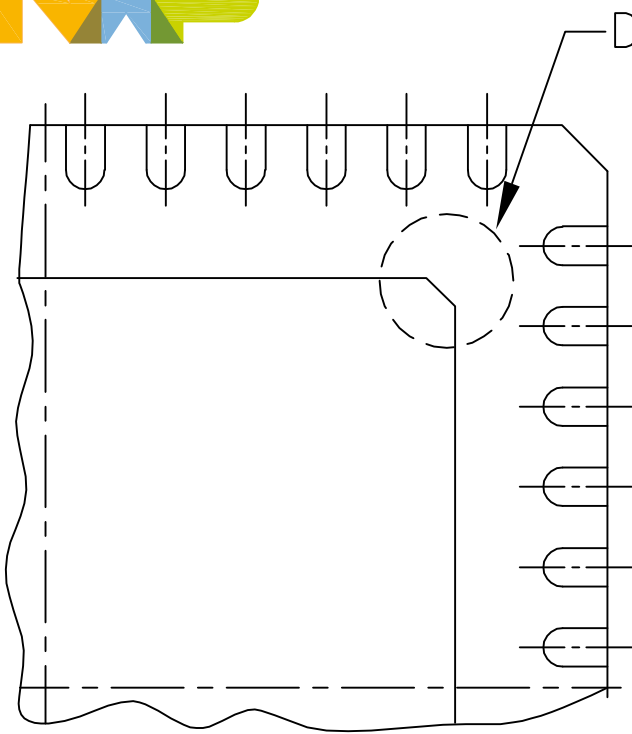


DETAIL N
CORNER CONFIGURATION OPTION

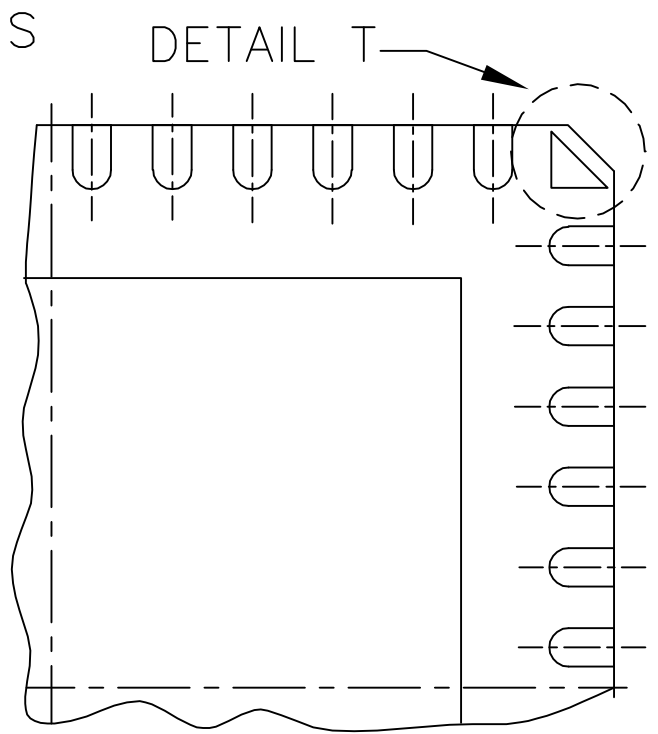


DETAIL G
VIEW ROTATED 90° CW

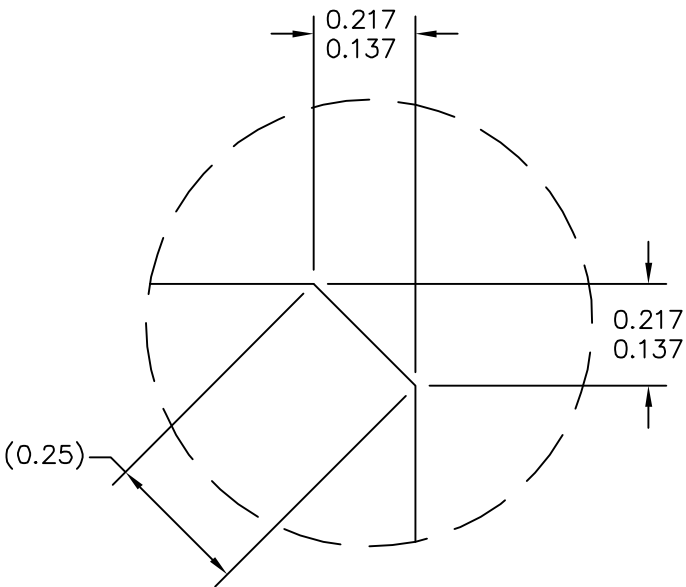
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 48 TERMINAL, 0.5 PITCH (7 X 7 X 1)	DOCUMENT NO: 98ASA10676D	REV: A
	STANDARD: JEDEC-MO-220 VKKD-2	
	SOT619-20	11 MAR 2016



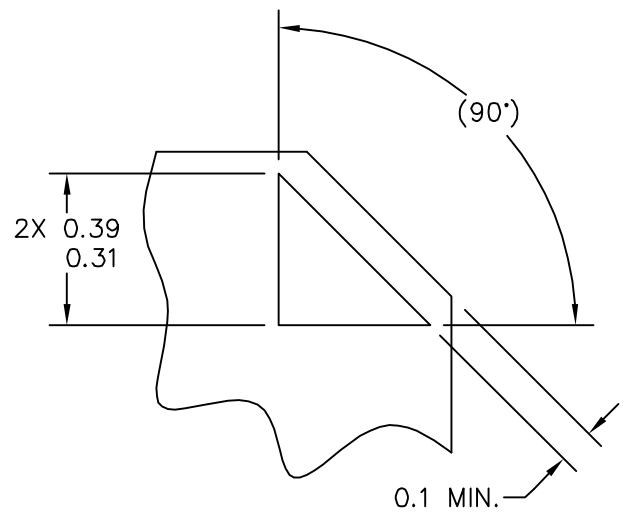
DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL M
BACKSIDE PIN 1 INDEX OPTION



DETAIL S
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL T
BACKSIDE PIN 1 INDEX OPTION

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	STANDARD: JEDEC-MO-220 VKKD-2	
	SOT619-20	11 MAR 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. DIMENSIONS OF OPTIONAL FEATURES ARE FOR REFERENCE ONLY.
5. COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
6. FOR ANVIL SINGULATED QFN PACKAGES, MAXIMUM DRAFT ANGLE IS 12°.
7. MIN METAL GAP SHOULD BE 0.25MM.

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